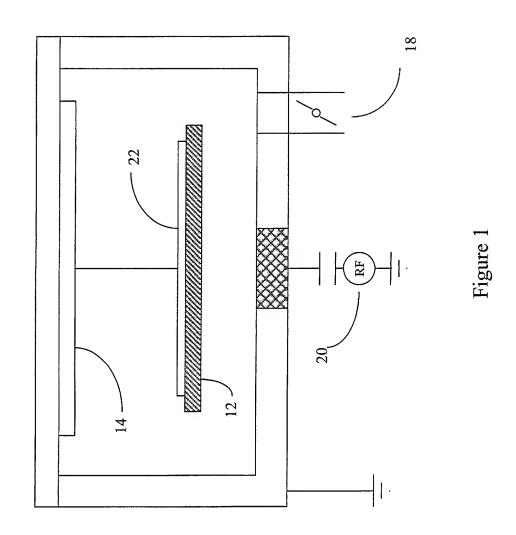
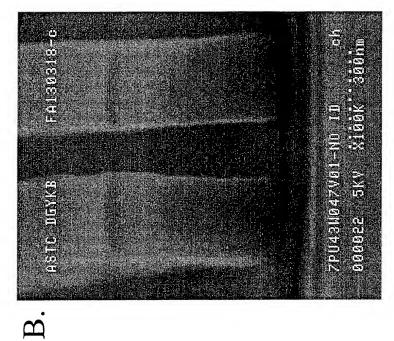
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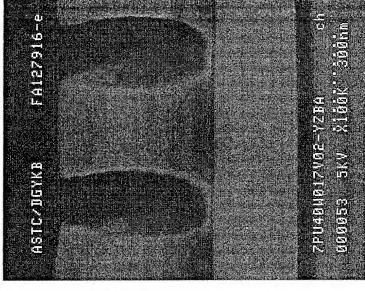


SiCOH low k dielectric film formed from 3MS and non-nitrogen containing oxidant

SiCOH low k dielectric film formed from

3MS and N<sub>2</sub>O oxidant

Figure 2



j

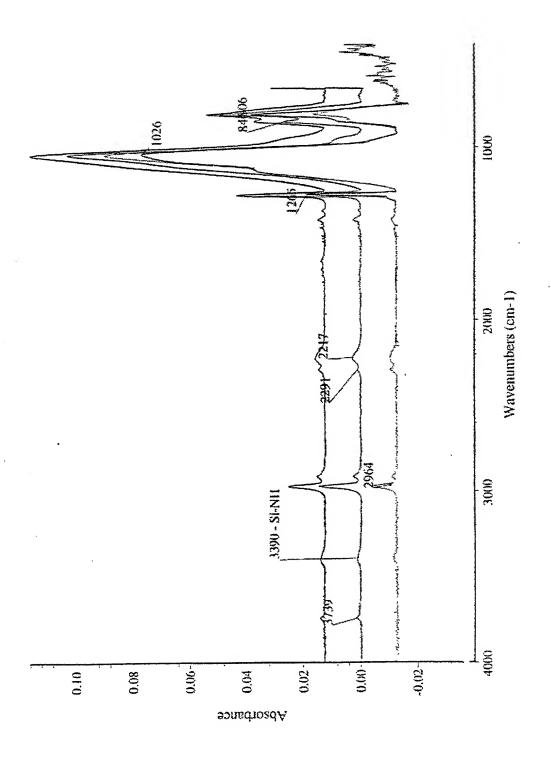


Figure 3

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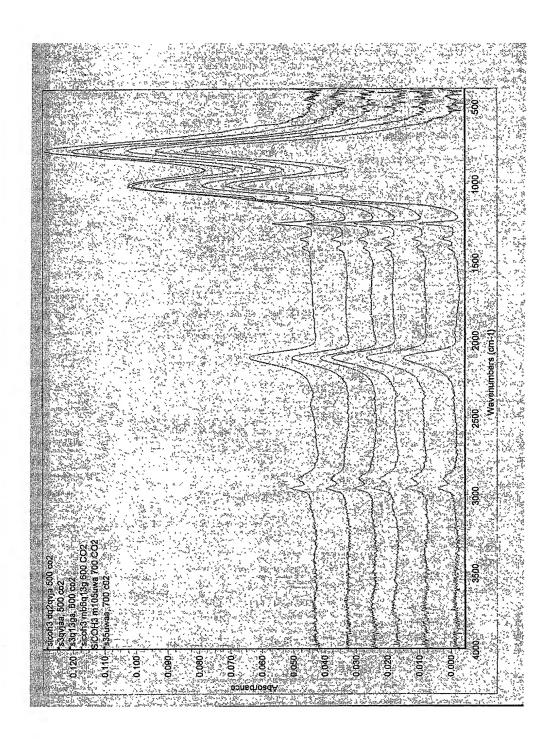


Figure 4